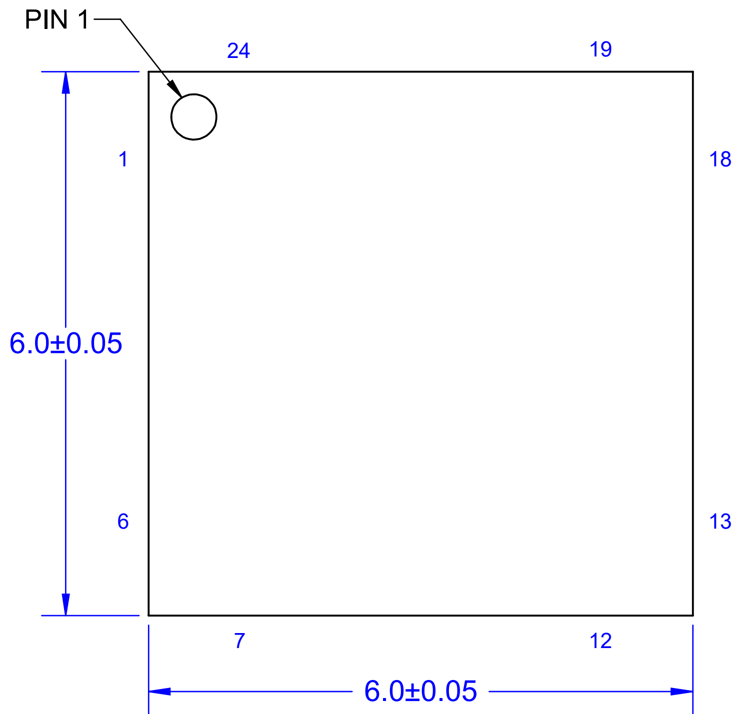
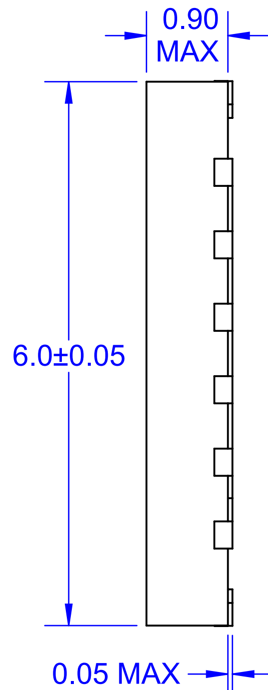
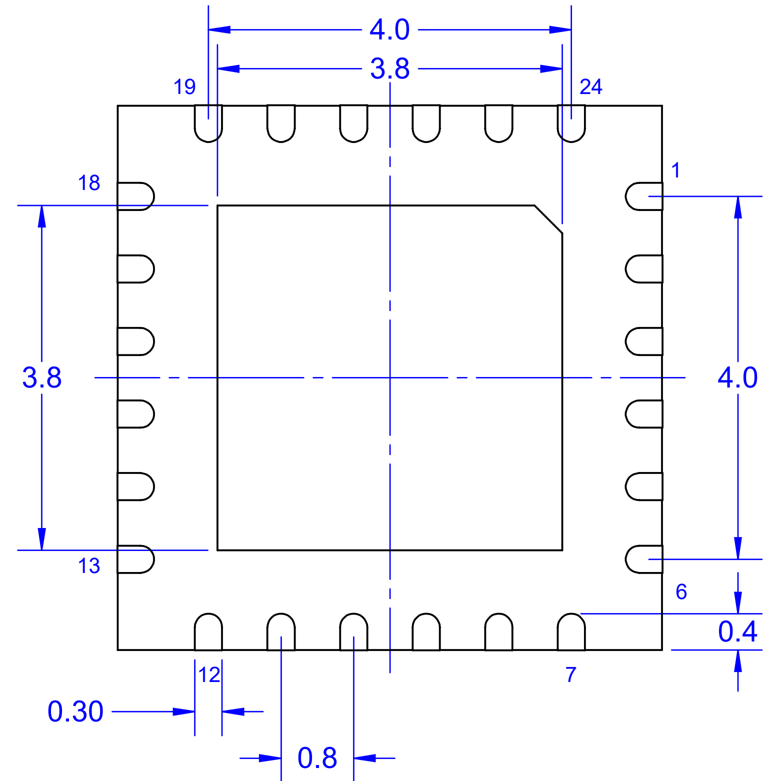
TOP VIEW



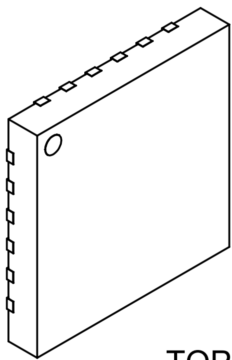
SIDE VIEW

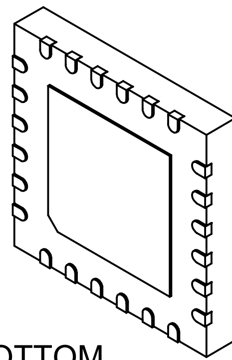


BOTTOM VIEW



MODEL



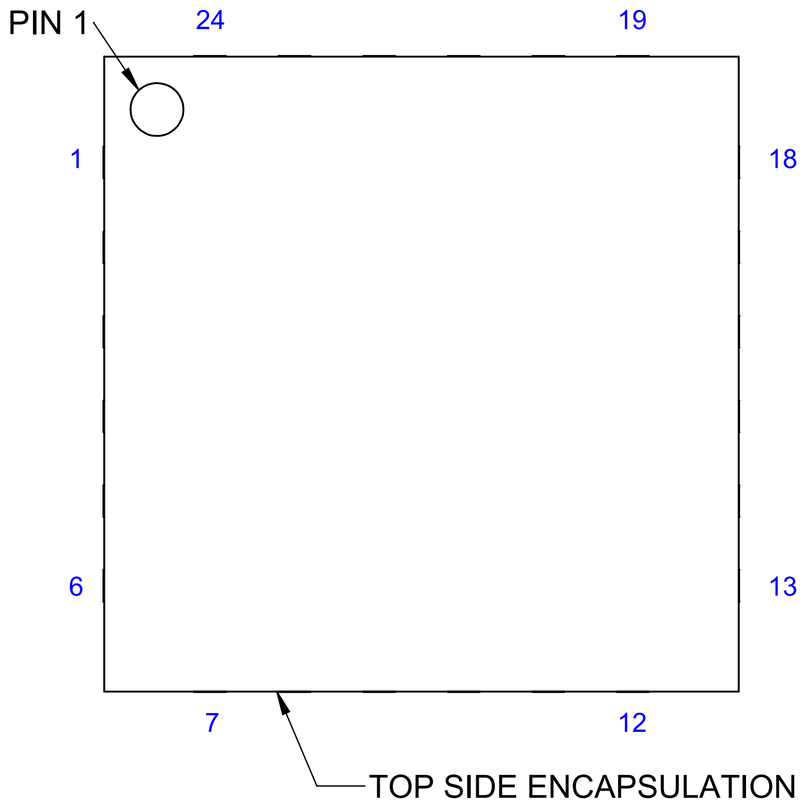


Notes: (Unless Otherwise Specified).
1) BODY: PLASTIC, SEMICONDUCTOR GRADE.
2) LEAD FRAME: COPPER, C-194 F/H.
3) LEAD FRAME PLATING: Sn100 MATTE TIN.
4) FRAME THICKNESS: 0.203mm.
5) DIE PAD: 3.8 x 3.8mm EXPOSED BOTTOM.
6) JEDEC OUTLINE: MO-220.
7) DIMENSIONS IN mm.

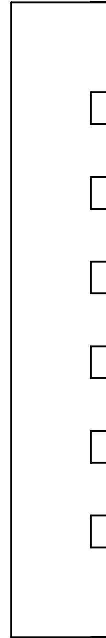
APPROVALS		DATE	TopLine®			
DRAWN	T.Au	6/11/2022				
ENG	M. Hart	6/11/2022	TITLE	24 LEAD 6mm P0.8mm QFN DAISY CHAIN		
MFG						
QA			SCALE 12:1	SIZE A	DRAWING NO. 482400	REV A
CUST						
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 5

DAISY CHAIN PATTERN

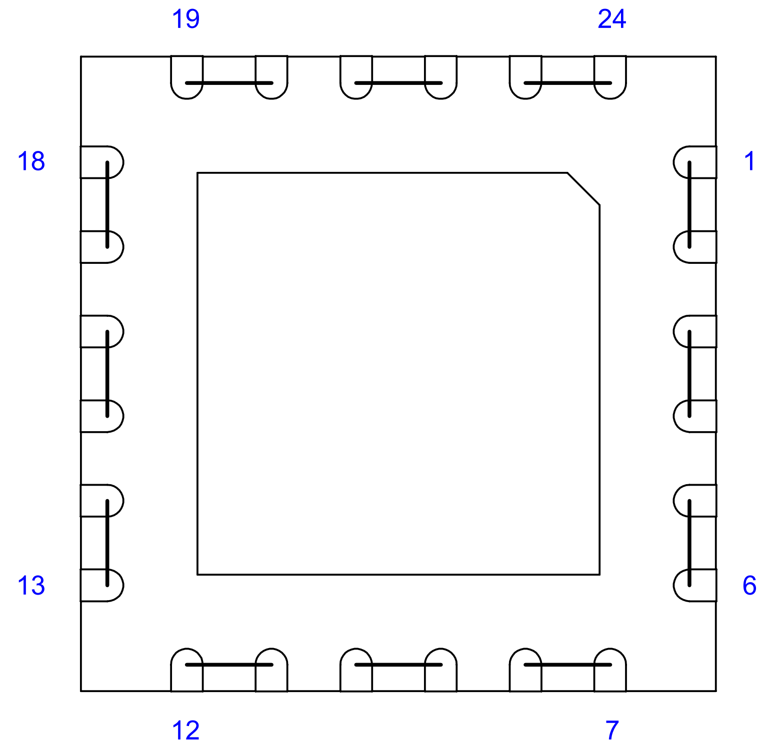
TOP VIEW



SIDE VIEW

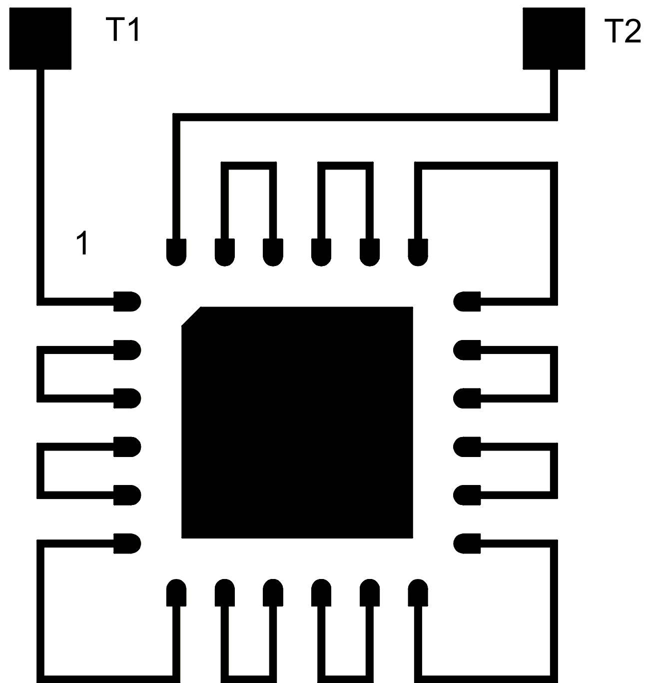


BOTTOM VIEW

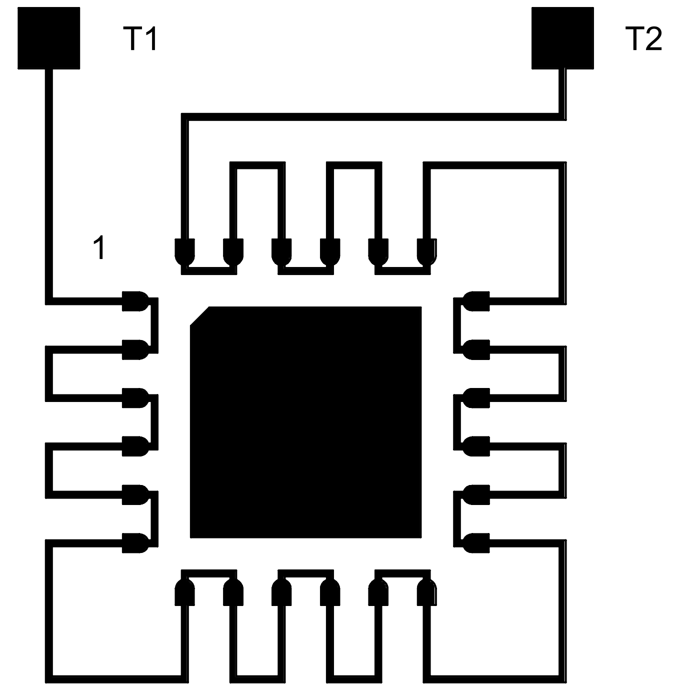


NOTE:
1. PACKAGE DAISY CHAIN BY WIRE BONDING TO INTERNAL BOND PADS.

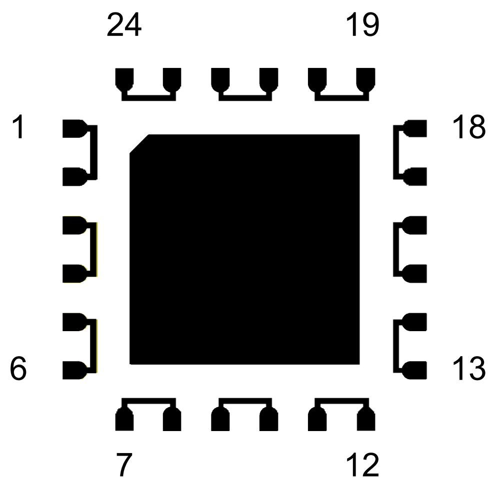
TopLine®			
TITLE	24 LEAD 6mm P0.8mm QFN DAISY CHAIN		
SCALE 14:1	SIZE A	DRAWING NO. 482400	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 5	



RECOMMENDED
PCB PADS

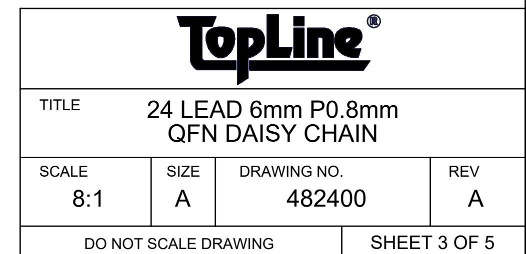


AFTER MOUNTING
ON PCB



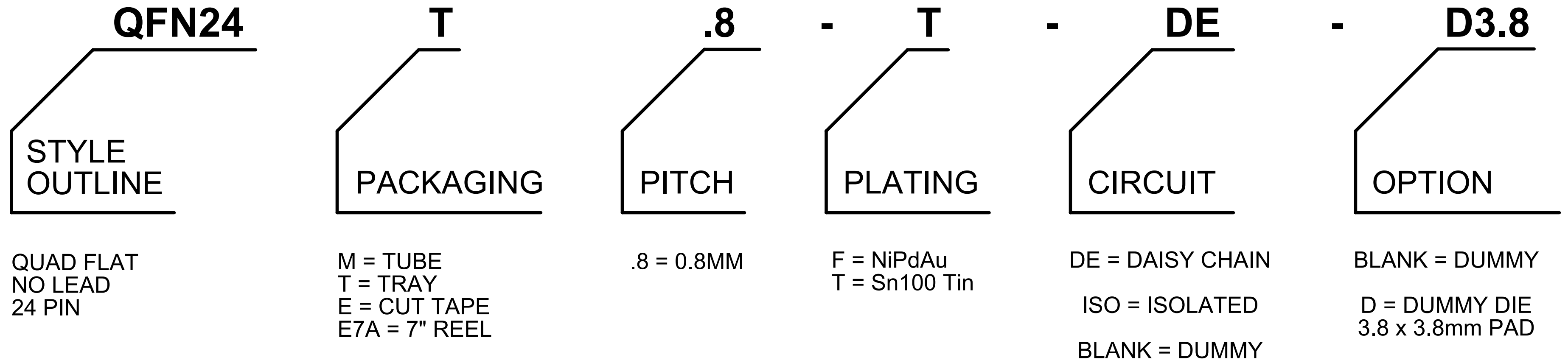
QFN

DAISY CHAIN NET LIST	
PINS	PINS
1 ~ 2	3 ~ 4
5 ~ 6	7 ~ 8
9 ~ 10	11 ~ 12
13 ~ 14	15 ~ 16
17 ~ 18	19 ~ 20
21 ~ 22	23 ~ 24



TITLE	24 LEAD 6mm P0.8mm QFN DAISY CHAIN		
SCALE 8:1	SIZE A	DRAWING NO. 482400	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 5	

PART NUMBERING SYSTEM



QUAD FLAT
NO LEAD
24 PIN

M = TUBE
T = TRAY
E = CUT TAPE
E7A = 7" REEL

.8 = 0.8MM

F = NiPdAu
T = Sn100 Tin

DE = DAISY CHAIN

ISO = ISOLATED

BLANK = DUMMY

BLANK = DUMMY

D = DUMMY DIE
3.8 x 3.8mm PAD

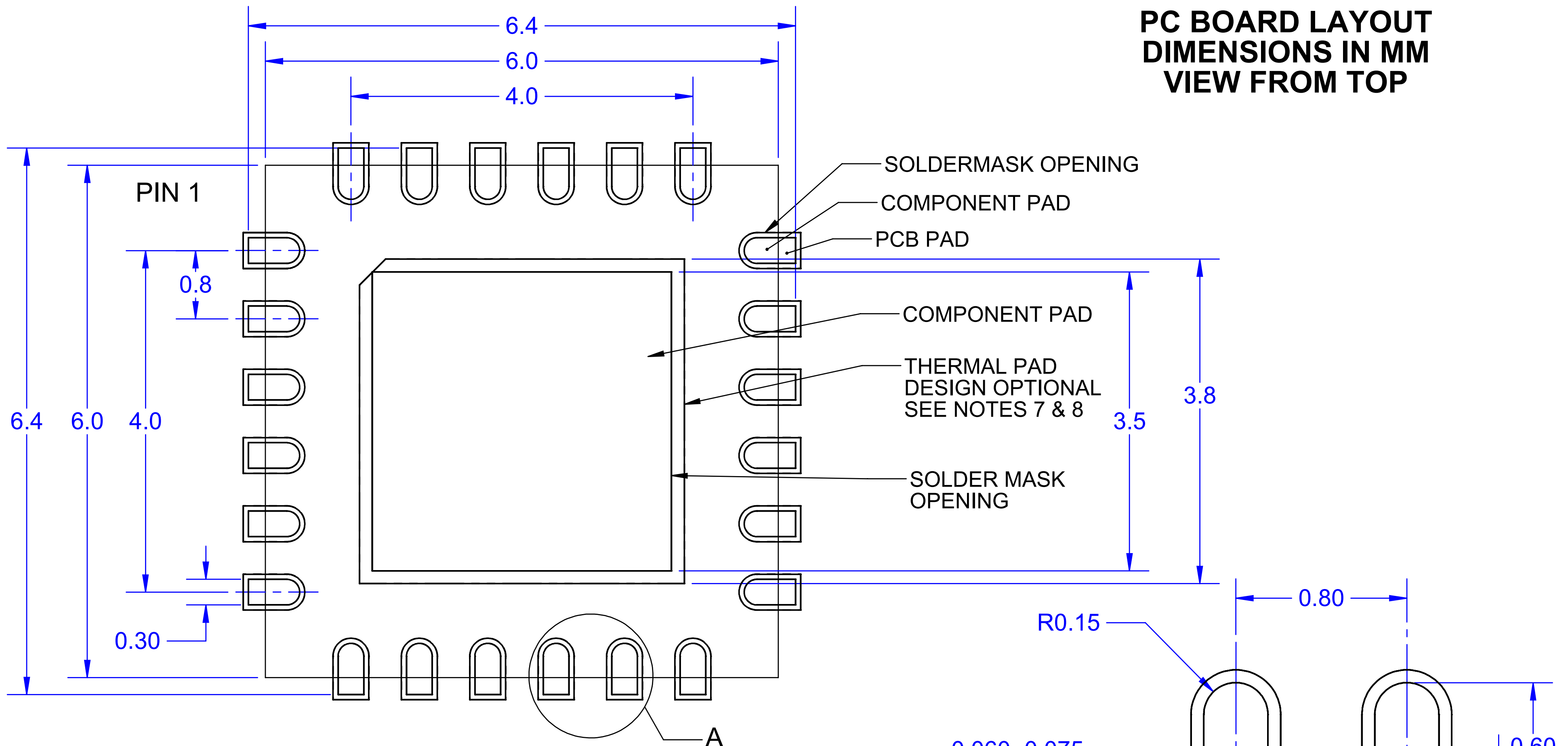
PART NUMBER	DAISY CHAIN	PACKAGING	RoHS Pb-FREE	MSL LEVEL	DUMMY DIE
QFN24T.8-T-DE-D3.8	YES	JEDEC TRAY	YES	1	YES
QFN24E.8-T-DE-D3.8	YES	CUT TAPE	YES	1	YES
QFN24E7A.8-T-DE-D3.8	YES	TAPE & REEL	YES	1	YES
QFN24M.8-T-DE-D3.8	YES	TUBE	YES	1	YES

OTHER PART NUMBER COMBINATIONS AVAILABLE. CONTACT TOPLINE.

TopLine®

TITLE	24 LEAD 6mm P0.8mm QFN DAISY CHAIN		
SCALE: NONE	SIZE: A	DRAWING NO.: 482400	REV: A

DO NOT SCALE DRAWING



Notes: (Unless Otherwise Specified).

1) DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN KNOWLEDGE BASE WHEN DESIGNING THE PCB.
2) SURROUND EACH SIDE OF I/O PERIMETER PADS WITH 0.060~0.075 mm (NSMD) SOLDER MASK OPENING (2.4~3.0mils) OPTIONALLY OK TO USE RECTANGLE (NSMD) MASK OPENING AROUND I/O PADS.
3) ROUNDED PCB LAND PADS REDUCE SOLDER BRIDGING. PAD CHAMFER ANGLE MAY VARY.
4) PCB LANDS SHOULD BE 0.2mm LONGER THAN THE PACKAGE I/O PADS.
5) THE WIDTH OF PERIMETER PCB PADS SHOULD MATCH (1:1) THE WIDTH OF THE PACKAGE PADS.
6) REFER TO INDUSTRY REFERENCES SUCH AS IPC-SM-782 FOR PCB LAND PATTERN DESIGN.
7) THERMAL GROUND PADS MAY BE CHANGED TO SUITE REQUIREMENTS OF THE DESIGNER.
   - A) MAKE COPPER THERMAL PAD AS LARGE AS POSSIBLE.
   - B) DRILL MULTIPLE THERMAL VIAS 0.25~0.33mm DIAMETER USING 0.8~1.2mm PITCH GRID.
   - C) PLATE THERMAL VIA BARRELS WITH 1-OUNCE COPPER (18μm).
   - D) TENT (COVER) THERMAL VIAS WITH SOLDER MASK 0.1mm LARGER THAN THE VIA DIAMETER.
8) STENCIL DESIGN MAY BE CHANGED TO SUIT REQUIREMENTS OF THE DESIGNER.
   - A) LASER CUT STENCIL 0.125mm (5mil) THICK. APERTURE SIZE-TO-LAND RATIO OF 1:1.
   - B) THE SOLDER PASTE OPENING IN THE THERMAL PAD AREA SHOULD BE A MATRIX ARRAY OF SMALLER APERATURES INSTEAD OF ONE LARGE APERATURE TO CONTROL PASTE AMOUNTS.
   - C) APPLY 50% TO 80% SOLDER PASTE COVERAGE IN THE PAD AREA.

TopLine®			
TITLE	24 LEAD 6mm P0.8mm QFN DAISY CHAIN		
SCALE 18:1	SIZE A	DRAWING NO. 482400	REV A
DO NOT SCALE DRAWING		SHEET 5 OF 5	